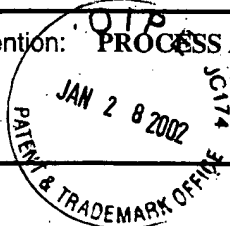


AMENDMENT TRANSMITTAL LETTER (Large Entity)

Applicant(s): John Rosato et al

Docket No.

SCP 6630

Serial No.
09/408,279Filing Date
29 September 1999Examiner
KornakovGroup Art Unit
1746Invention: **PROCESS AND SYSTEM FOR RINSING OF SEMICONDUCTOR SUBSTRATES****TO THE ASSISTANT COMMISSIONER FOR PATENTS:**

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	32 -	79 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	5 -	9 =	0 x	\$84.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

- ☒ No additional fee is required for amendment.
- ☐ Please charge Deposit Account No. _____ in the amount of _____
A duplicate copy of this sheet is enclosed.
- ☐ A check in the amount of _____ to cover the filing fee is enclosed.
- ☐ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. _____
A duplicate copy of this sheet is enclosed.
- ☐ Any additional filing fees required under 37 C.F.R. 1.16.
- ☐ Any patent application processing fees under 37 CFR 1.17.

Signature

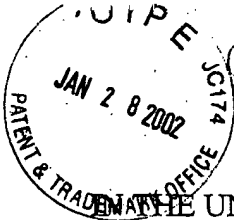
Dated: 23 October 2001

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TC 1700Kathleen A. Frost
Reg. No 37,326STALLMAN & POLLOCK L.L.P.
121 Spear Street; Suite 290
San Francisco, CA 94105I certify that this document and fee is being deposited
October 23, 2001 with the U.S. Postal Service as
first class mail under 37 C.F.R. 1.8 and is addressed to the
Assistant Commissioner for Patents, Washington, D.C.
20231.

Signature of Person Mailing Correspondence

Typed or Printed Name of Person Mailing Correspondence

CC:



PATENT

-1-

UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Rosato et al Application No.: 09/408,279 Filed: September 29, 1999 For: PROCESS AND SYSTEM FOR RINSING OF SEMICONDUCTOR SUBSTRATES	Group No.: 1746 Examiner: Kornakov RESPONSE TO RESTRICTION REQUIREMENT MAILED APRIL 23, 2001
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Commissioner for Patents
Washington, DC 20231

Sir:

Applicants make the following amendments and remarks in response to the official action mailed April 23, 2001.

In the Claims

Please cancel Claims 1 - 79 without prejudice, and add new claims 80 - 111.

80. (NEW) A method for rinsing metallized semiconductor substrates with an aqueous medium comprising including in said aqueous medium an amount effective to minimize metal corrosion of an anti-corrosive agent including an organic compound.

81. (NEW) The method of claim 80 wherein the organic compound includes an organic acid.

82. (NEW) A method according to claim 80 in which the organic acid includes includes an organic carboxylic acid.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope, addressed to: Commissioner for Patents, Washington, DC 20231 on 23 October 2001

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